VERN LIANG

San Francisco Bay Area | 949-439-1843 | vliang@gmail.com | www.linkedin.com/in/vwliang

Technically oriented Senior Product Manager with over 10 years of experience, an MBA and MSCS, specializing in HW/SW product development and launching innovative solutions for smartphones & IOT devices with global cross-functional teams.

EXPERIENCE

Senior Product Manager – Intel Corporation   Santa Clara, CA   2015-2021
- Led security design lifecycle integration of CDMA IP into XMM7560 chipset that was featured in 2018 iPhones, **increased business unit revenue 131% YoY**. See [Motley Fool article: "This Intel Product Stood Out in 2018"](#).
- Defined CBP7.2 Baseband Modem Product, which **shipped in >30MM** Huawei smartphones in China.
- Owned entire CDMA product roadmap (RF, Baseband Modem, PMU), **$80MM annual revenue** for Intel.
- Defined product features for cryptography core and coded Python validation scripts for 5G Test Platform.

Principal Product Manager – VIA Telecom, Inc   San Diego, Fremont, CA   2009-2015
VIA Telecom produced CDMA2000 modems for smartphones, [acquired by Intel in 2015](#). Global Lead Product Manager, worked closely with CEO and CTO to create and define new chipset products, led teams based in America and China.
- **Launched 7 chipset products** that **shipped in >10MM** Samsung Android smartphones (e.g., [Samsung Galaxy Nexus](#)).
- Spearheaded IOT module certification for OEMs in Tier 1 carriers (Verizon, Sprint), managed API feature customization for IOT module vendors, **shipped over 250k** IOT modules.
- Led product name rebranding across all VIA Telecom products and presented roadmaps to customers at CES.

Associate – Georgian Pine Investments, LLC   Menlo Park, CA   2007-2009
Tech Venture Capital fund that invested in Ad Tech companies in the US and China. BitAuto IPO in NYSE, Blip.tv acquired.
- Invested in BitAuto (**acquired for $1.1 Billion** by Tencent) and Quantcast (**$300MM valuation**).
- Authored Annual Financial Report to investors, performed due diligence on early stage advertising tech companies.

Staff HW Engineer – Broadcom Corporation   San Diego, Irvine, CA   2003-2007
1st new grad hire into core Bluetooth team of 6 architects, designed wireless chips that shipped in the Apple iPhone, iPad
- Led Bluetooth-WiFi chip simulation in **world's first Bluetooth-WiFi combo products**. BT-WiFi chips **shipped in 400MM iPhones** (3GS, 4) and **100MM iPads** (Gen 1,2).
- Designed, tested, validated features in **4 Bluetooth chips** that **shipped in Motorola RAZR** (World's best selling flip phone: **130MM units**), **Nintendo Wii** and Wii Remotes (**202MM units**), Apple Magic Mouse. Coded in Verilog RTL.
- Created new chip-to-chip protocol, led interoperability tests with partners for Broadcom's first ARM Bluetooth chips.
- Designed a chip memory screening program that **saved the company over $10MM** on the production line.

EDUCATION

University of Illinois Urbana-Champaign   2021-2022
MBA, Specializations in **Business Analytics** and **Digital Marketing**, GPA 4.0/4.0
- Graduated in 1 year from 2-year MBA program, Top 10% of UIUC Graduate Students, 14 A+ out of 19 Courses

Georgia Institute of Technology   2018-2020
MS in **Computer Science**, Specialization in **Machine Learning**, GPA 3.8/4.0

University of California, Berkeley   1999-2003
BS in **Electrical Engineering and Computer Science**
- Prof. Sherman Frankel Research Group (*Anti-Snore Sound Project: designed ultrasonic rangefinder*)

ACTIVITIES & AWARDS

Phi Kappa Phi (Top 10% of UIUC Graduate Student Class), Beta Gamma Sigma (Top 20% of MBA Class), Ranked 1 of 620 at Irvine High School (Valedictorian), Intel Toastmasters President 2017-2018

ADDITIONAL INFO

Certified Scrum Product Owner, Python, R, SQL, Java (Developed Android App Game), Tableau, US Citizen